

# Surface Mount Schottky Power Rectifier

**POWERMITE®**
**Power Surface Mount Package**
**MBRM130LT1G,  
NRVBM130LT1G,  
MBRM130LT3G,  
NRVBM130LT3G**

The SchottkyPOWERMITE® employs the Schottky Barrier principle with a barrier metal and epitaxial construction that produces optimal forward voltage drop–reverse current tradeoff. The advanced packaging techniques provide for a highly efficient micro miniature, space saving surface mount Rectifier. With its unique heatsink design, thePOWERMITE® has the same thermal performance as the SMA while being 50% smaller in footprint area, and delivering one of the lowest height profiles, < 1.1 mm in the industry. Because of its small size, it is ideal for use in portable and battery powered products such as cellular and cordless phones, chargers, notebook computers, printers, PDAs and PCMCIA cards. Typical applications are AC–DC and DC–DC converters, reverse battery protection, and “ORing” of multiple supply voltages and any other application where performance and size are critical.

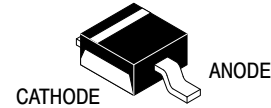
## Features

- Low Profile – Maximum Height of 1.1 mm
- Small Footprint – Footprint Area of 8.45 mm<sup>2</sup>
- Low V<sub>F</sub> Provides Higher Efficiency and Extends Battery Life
- Supplied in 12 mm Tape and Reel
- Low Thermal Resistance with Direct Thermal Path of Die on Exposed Cathode Heat Sink
- ESD Ratings:
  - ◆ Human Body Model = 3B (> 16 kV)
  - ◆ Machine Model = C (> 400 V)
- AEC–Q101 Qualified and PPAP Capable
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- All Packages are Pb–Free\*

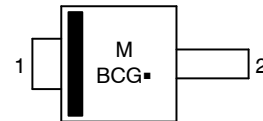
## Mechanical Characteristics:

- POWERMITE® is JEDEC Registered as D0–216AA
- Case: Molded Epoxy
- Epoxy Meets UL 94 V–0 @ 0.125 in
- Weight: 16.3 mg (Approximately)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Maximum for 10 Seconds

\*For additional information on our Pb–Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, [SOLDERRM/D](#).

**SCHOTTKY BARRIER  
RECTIFIER  
1.0 AMPERES, 30 VOLTS**

**POWERMITE  
CASE 457  
PLASTIC**

## MARKING DIAGRAM



M = Date Code  
BCG = Device Code  
■ = Pb–Free Package

## ORDERING INFORMATION

Device	Package	Shipping†
MBRM130LT1G	POWERMITE (Pb–Free)	3,000 / Tape & Reel
NRVBM130LT1G	POWERMITE (Pb–Free)	3,000 / Tape & Reel

## DISCONTINUED (Note 1)

MBRM130LT3G	POWERMITE (Pb–Free)	12,000 / Tape & Reel
NRVBM130LT3G	POWERMITE (Pb–Free)	12,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, [BRD8011/D](#).

1. **DISCONTINUED:** These devices are not recommended for new design. Please contact your **onsemi** representative for information. The most current information on these devices may be available on [www.onsemi.com](http://www.onsemi.com).

# MBRM130LT1G, NRVBM130LT1G, MBRM130LT3G, NRVBM130LT3G

## MAXIMUM RATINGS

Symbol	Rating	Value	Unit
$V_{RRM}$ $V_{RWM}$ $V_R$	Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	30	V
$I_O$	Average Rectified Forward Current (At Rated $V_R$ , $T_C = 135^\circ\text{C}$ )	1.0	A
$I_{FRM}$	Peak Repetitive Forward Current (At Rated $V_R$ , Square Wave, 100 kHz, $T_C = 135^\circ\text{C}$ )	2.0	A
$I_{FSM}$	Non-Repetitive Peak Surge Current (Non-Repetitive peak surge current, halfwave, single phase, 60 Hz)	50	A
$T_{stg}$	Storage Temperature	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature	-55 to 125	$^\circ\text{C}$
dv/dt	Voltage Rate of Change (Rated $V_R$ , $T_J = 25^\circ\text{C}$ )	10,000	V/ $\mu\text{s}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

## THERMAL CHARACTERISTICS

Symbol	Characteristic	Value	Unit
$R_{\theta j l}$	Thermal Resistance, Junction-to-Lead (Anode) (Note 1)	35	$^\circ\text{C}/\text{W}$
$R_{\theta j tab}$	Thermal Resistance, Junction-to-Tab (Cathode) (Note 1)	23	
$R_{\theta ja}$	Thermal Resistance, Junction-to-Ambient (Note 1)	277	

1. Mounted with minimum recommended pad size, PC Board FR4, See Figures 9 & 10

## ELECTRICAL CHARACTERISTICS

Symbol	Characteristic	Value		Unit
$V_F$	Maximum Instantaneous Forward Voltage (Note 2), See Figure 2  ( $I_F = 0.1\text{ A}$ ) ( $I_F = 1.0\text{ A}$ ) ( $I_F = 3.0\text{ A}$ )	$T_J = 25^\circ\text{C}$	$T_J = 85^\circ\text{C}$	V
		0.30 0.38 0.52	0.20 0.33 0.50	
$I_R$	Maximum Instantaneous Reverse Current (Note 2), See Figure 4  ( $V_R = 30\text{ V}$ ) ( $V_R = 20\text{ V}$ ) ( $V_R = 10\text{ V}$ )	$T_J = 25^\circ\text{C}$	$T_J = 85^\circ\text{C}$	mA
		0.41 0.13 0.05	11 5.3 3.2	

2. Pulse Test: Pulse Width  $\leq 250\text{ }\mu\text{s}$ , Duty Cycle  $\leq 2\%$

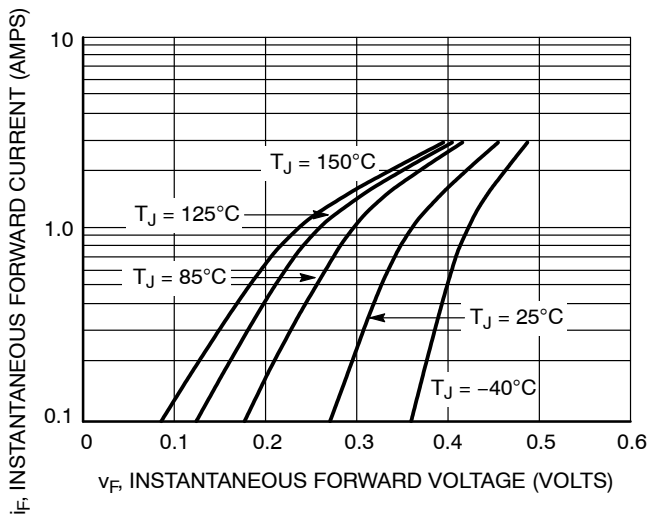


Figure 1. Typical Forward Voltage

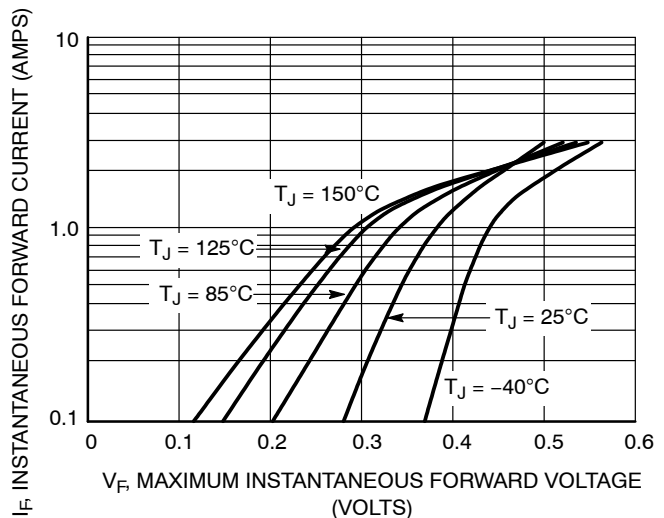


Figure 2. Maximum Forward Voltage

# MBRM130LT1G, NRVBM130LT1G, MBRM130LT3G, NRVBM130LT3G

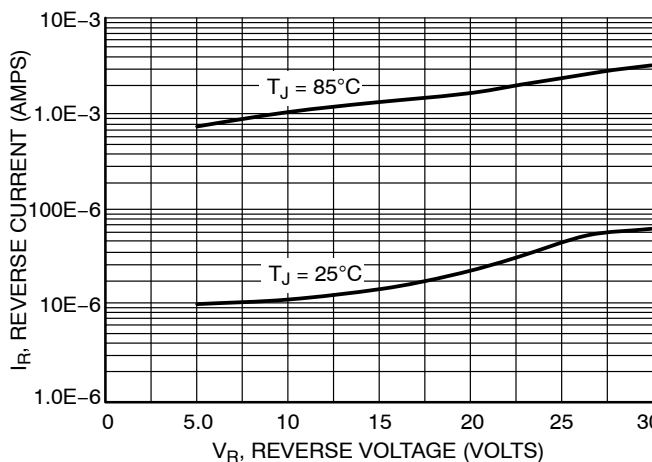


Figure 3. Typical Reverse Current

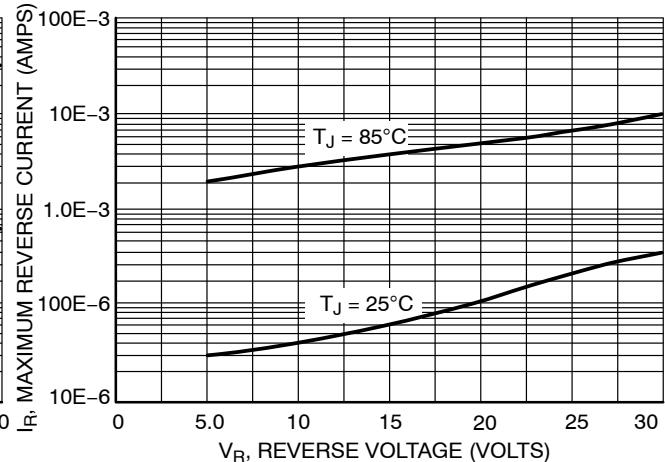


Figure 4. Maximum Reverse Current

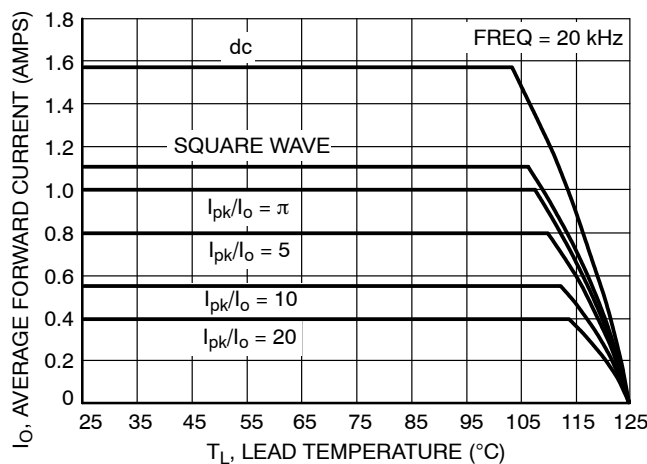


Figure 5. Current Derating

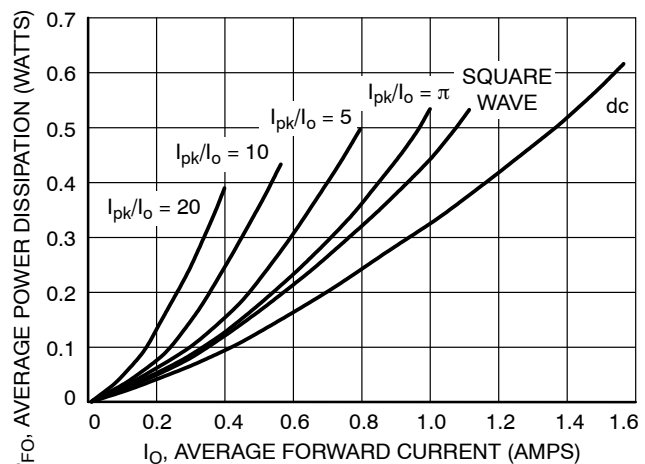


Figure 6. Forward Power Dissipation

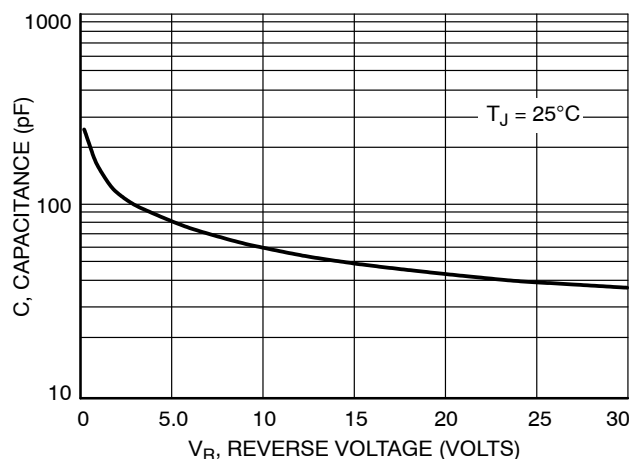


Figure 7. Capacitance

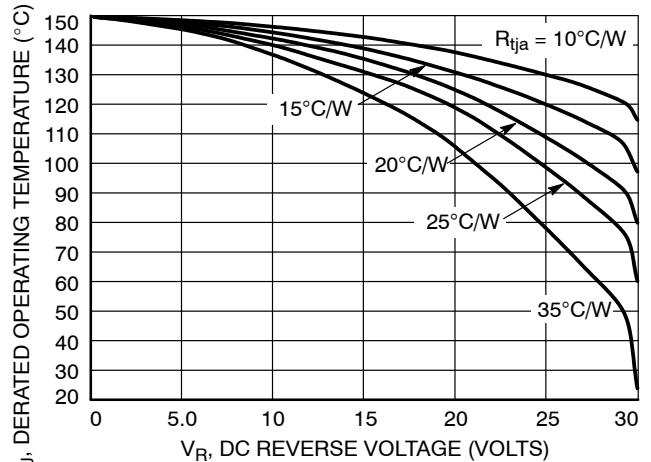


Figure 8. Typical Operating Temperature Derating\*

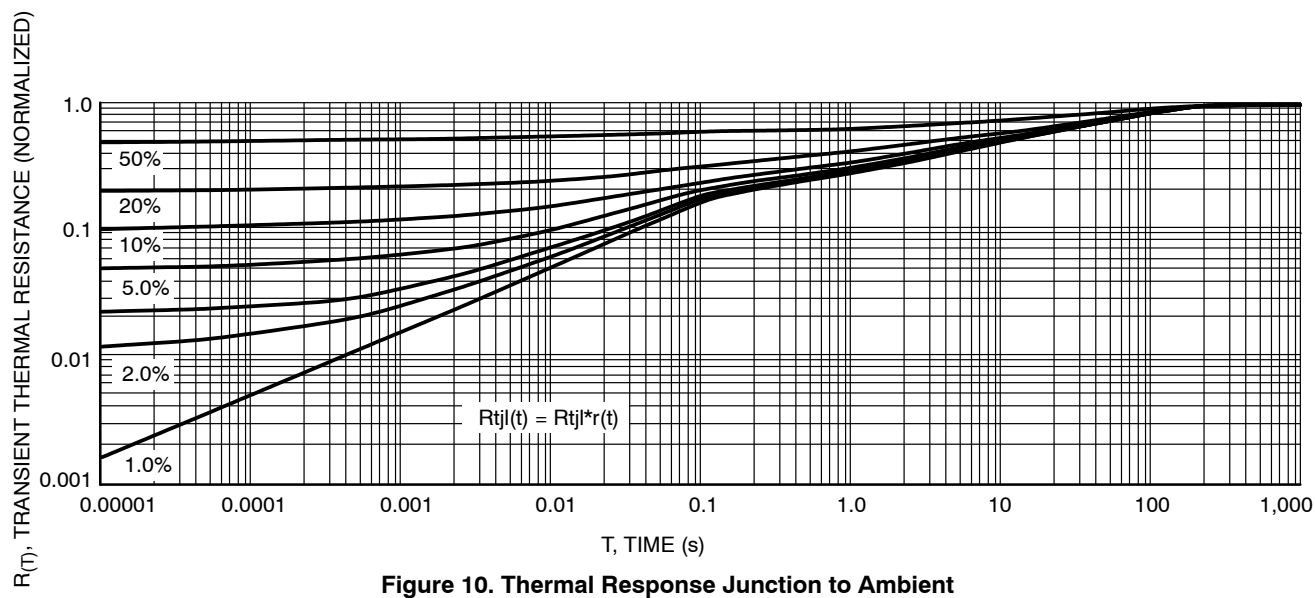
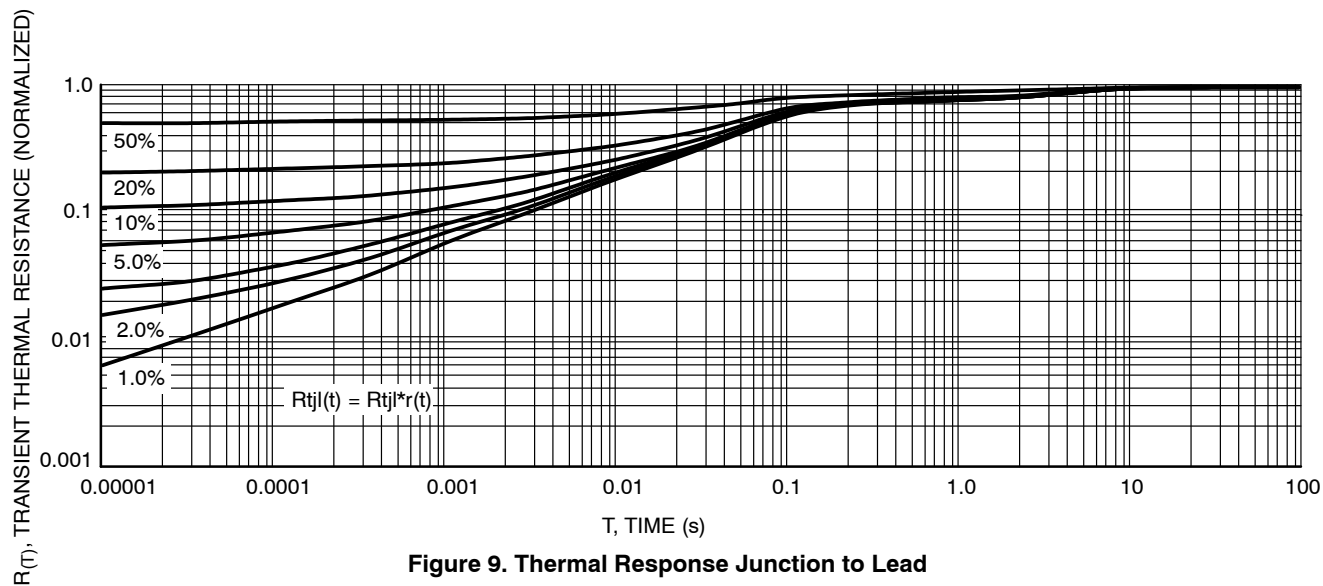
\* Reverse power dissipation and the possibility of thermal runaway must be considered when operating this device under any reverse voltage conditions. Calculations of  $T_J$  therefore must include forward and reverse power effects. The allowable operating  $T_J$  may be calculated from the equation:

$$T_J = T_{Jmax} - r(t)(P_f + P_r) \text{ where}$$

$r(t)$  = thermal impedance under given conditions,  
 $P_f$  = forward power dissipation, and  
 $P_r$  = reverse power dissipation

This graph displays the derated allowable  $T_J$  due to reverse bias under DC conditions only and is calculated as  $T_J = T_{Jmax} - r(t)P_r$ , where  $r(t) = R_{\theta ja}$ . For other power applications further calculations must be performed.

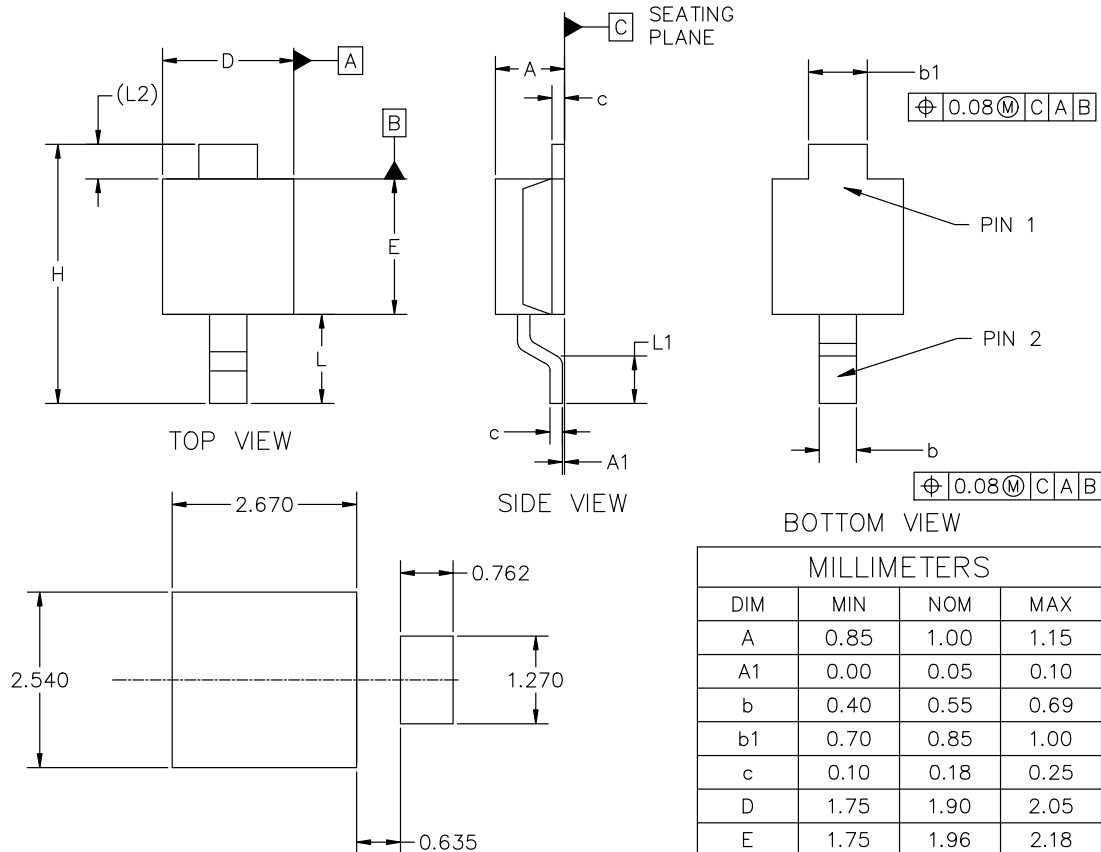
MBRM130LT1G, NRVBM130LT1G, MBRM130LT3G, NRVBM130LT3G



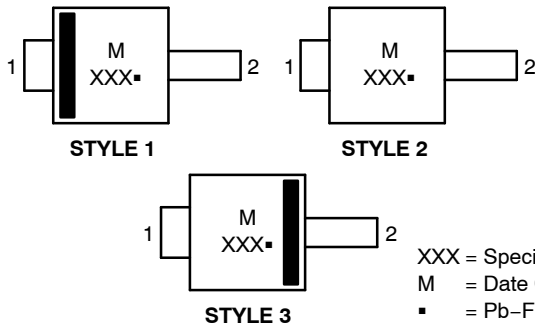
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**POWERMITE 1.90x1.96x1.00**  
**CASE 457**  
**ISSUE H**

DATE 16 MAY 2025


**RECOMMENDED MOUNTING FOOTPRINT**

\*For additional information on our Pb-Free Strategy and Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**GENERIC MARKING DIAGRAMS\***


XXX = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

**NOTES:**

1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

STYLE 1:  
PIN 1: CATHODE  
2: ANODE

STYLE 2:  
PIN 1: ANODE OR CATHODE  
2: CATHODE OR ANODE (BI-DIRECTIONAL)

STYLE 3:  
PIN 1: ANODE  
2: CATHODE

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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